IN THE ABSTRACT

Change the paragraph beginning at Page 25, line 4 to read as follows:

To form a spin valve device, start by forming a gap layer. Form a buffer layer with a layer of
refractory material on the buffer layer. Form patterned underlayers including a magnetic material for
providing trackwidth and longitudinal bias on the buffer layer comprising either a lower
antiferromagnetic layer stacked with a ferromagnetic layer or a Cr layer stacked with a permanent
magnetic layer. Form an inwardly tapered depression in the patterned underlayers down to the buffer
layer by either ion milling through a mask or a stencil lift off technique. Form layers covering the
patterned underlayers that cover the inwardly tapered depression. Form free, pinned, spacer and
antiferromagnetic layers. Form conductors either on a surface of the antiferromagnetic layer aside from
the depression or between the buffer layer and the patterned underlayers